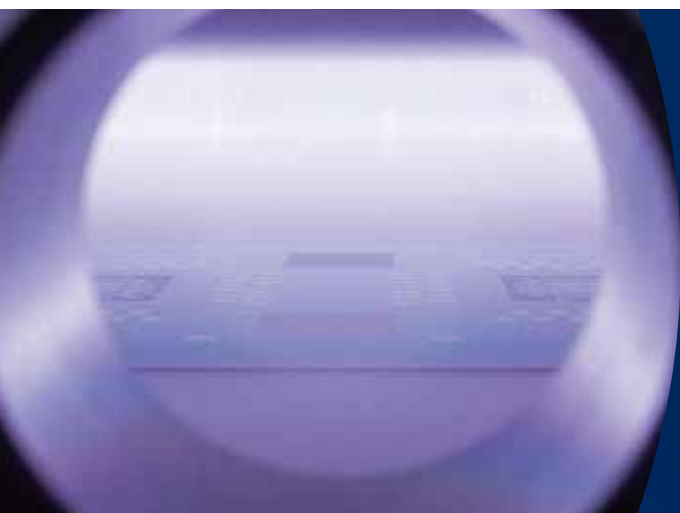


Model ID

# PSX307A

Model No.

## NM-EFP3A



### For substrate & wafer level PKG

- Surface cleaning and modification of wafers and substrates improve bondability of metal and adhesion of resin.
- Increasing process number of wafers and substrates in the same time by enlarging vacuum chamber capacity improves productivity.
- Panasonic original plasma monitoring system suppresses abnormal discharge and newly introduced traceability function ensures process quality.
- Flexible machine concept adapts versatile production model and supports process operation.
- Capability of  $\Phi 300$  mm wafer ( with / without : dicing ring ) contributes to wafer level package manufacturing.

Model ID	PSX307A
Model No.	NM-EFP3A
Cleaning Method	Parallel plate RF back-sputtering method
Gas for Electrical Discharge <sup>*1</sup>	Ar ( Option : O <sub>2</sub> , O <sub>2</sub> + He )
Power source	1-phase AC 200 / 208 / 220 / 230 / 240 $\pm 10$ V , 50 / 60 Hz , 6.00 kVA
Pneumatic source	0.49 MPa , 50 L / min ( A.N.R. )
Dimension <sup>*2</sup>	W 900 mm $\times$ D 1 150 mm $\times$ H 1 650 mm
Mass <sup>*3</sup>	630 kg

Specification ( Target work ) <sup>*4</sup>	Substrate	Wafer with dicing ring	Wafer without dicing ring
Work Size <sup>*5</sup>	L 50 mm $\times$ W 30 mm <sup>*6</sup> to L 350 mm $\times$ W 350 mm	$\Phi 300$ <sup>*7</sup>	$\Phi 300$

Please refer to the specifications on details.

Pre-confirmation by customer's works is required.

<sup>\*1</sup> : If the optional oxygen gas is selected as electric discharge gas , nitrogen gas is also required to dilute exhaust.

<sup>\*2</sup> : Excluding touch panel, emergency stop switch and signal tower.

<sup>\*3</sup> : In case of full option

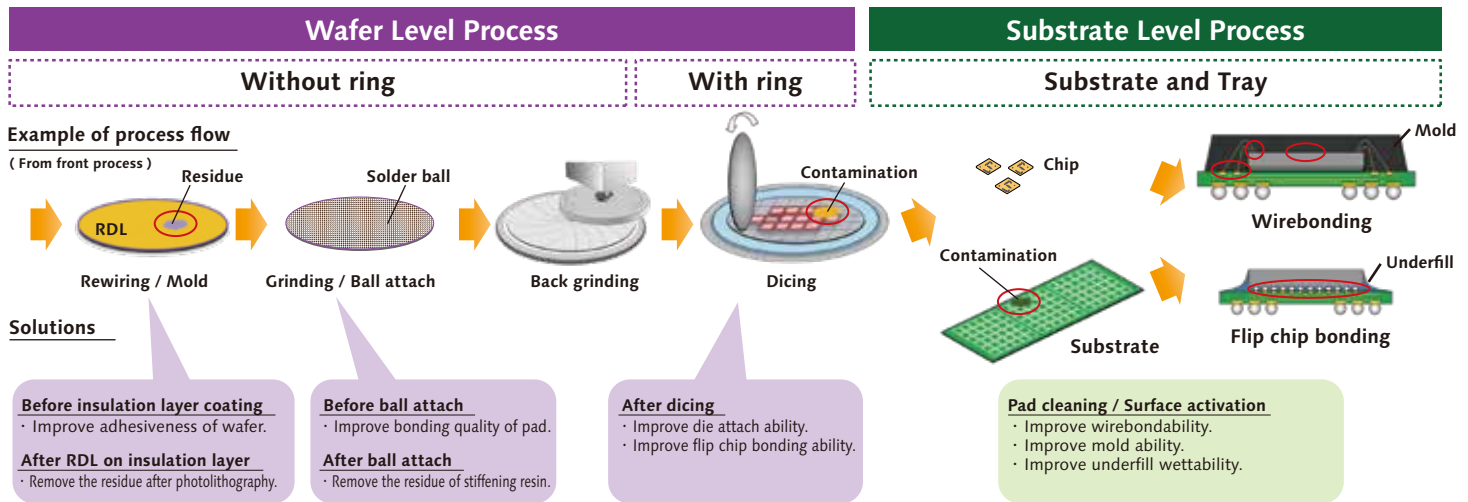
<sup>\*4</sup> : Please select a specification among three.

<sup>\*5</sup> : Please consult us about the substrate thickness.

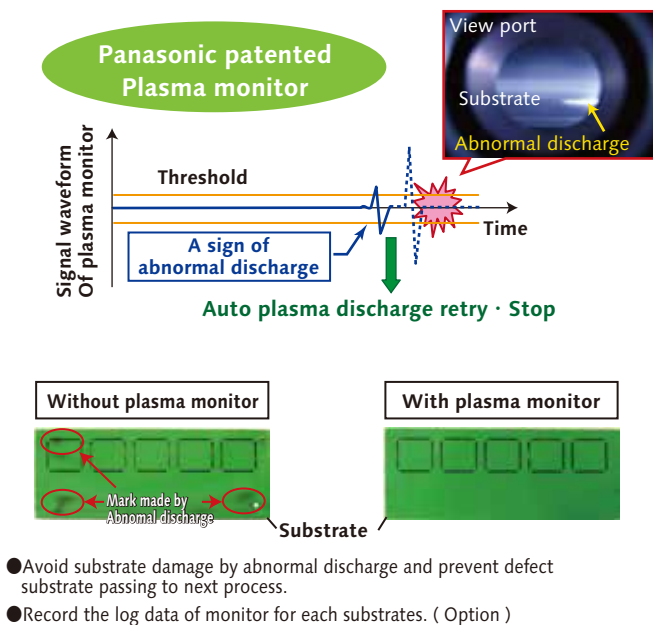
<sup>\*6</sup> : Please contact us for the substrate with depth < 30 mm.

<sup>\*7</sup> : outer diameter of ring :  $\square 380$  mm

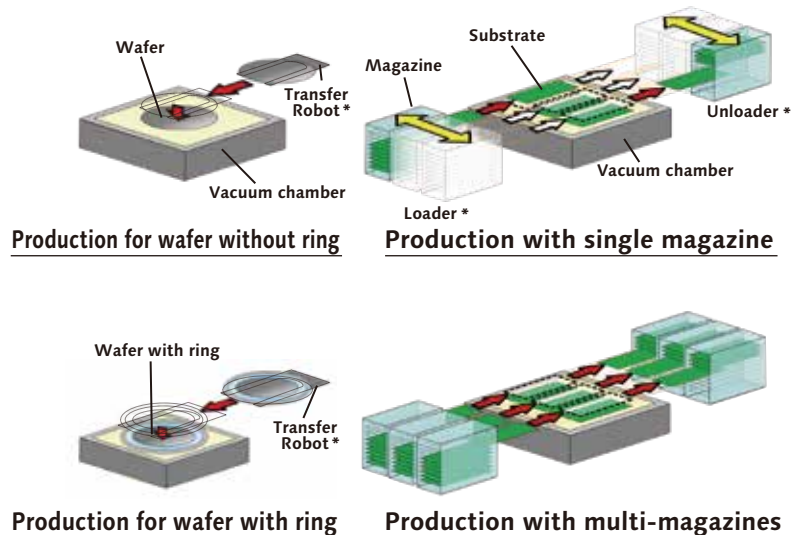
# Achieve high quality production by plasma cleaning and modification from wafer level to substrate level assembly process



## High quality management with plasma monitor



## Flexibility for various type of production



\* Transfer robot, loader / unloader are prepared by customer.

## ⚠ Safety Cautions

- Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.
- To ensure safety when using this equipment, all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

Panasonic Group products are built with the environment in mind.

For details here



Panasonic GREEN IMPACT

Inquiries...

Panasonic Connect Europe GmbH  
Factory Solutions  
Caroline-Herschel-Straße 100  
85521 Ottobrunn  
Germany

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- Changes in specifications and appearance may be made without notice for product improvement.
- Please contact us via our website at [connect.panasonic.eu](https://connect.panasonic.eu)